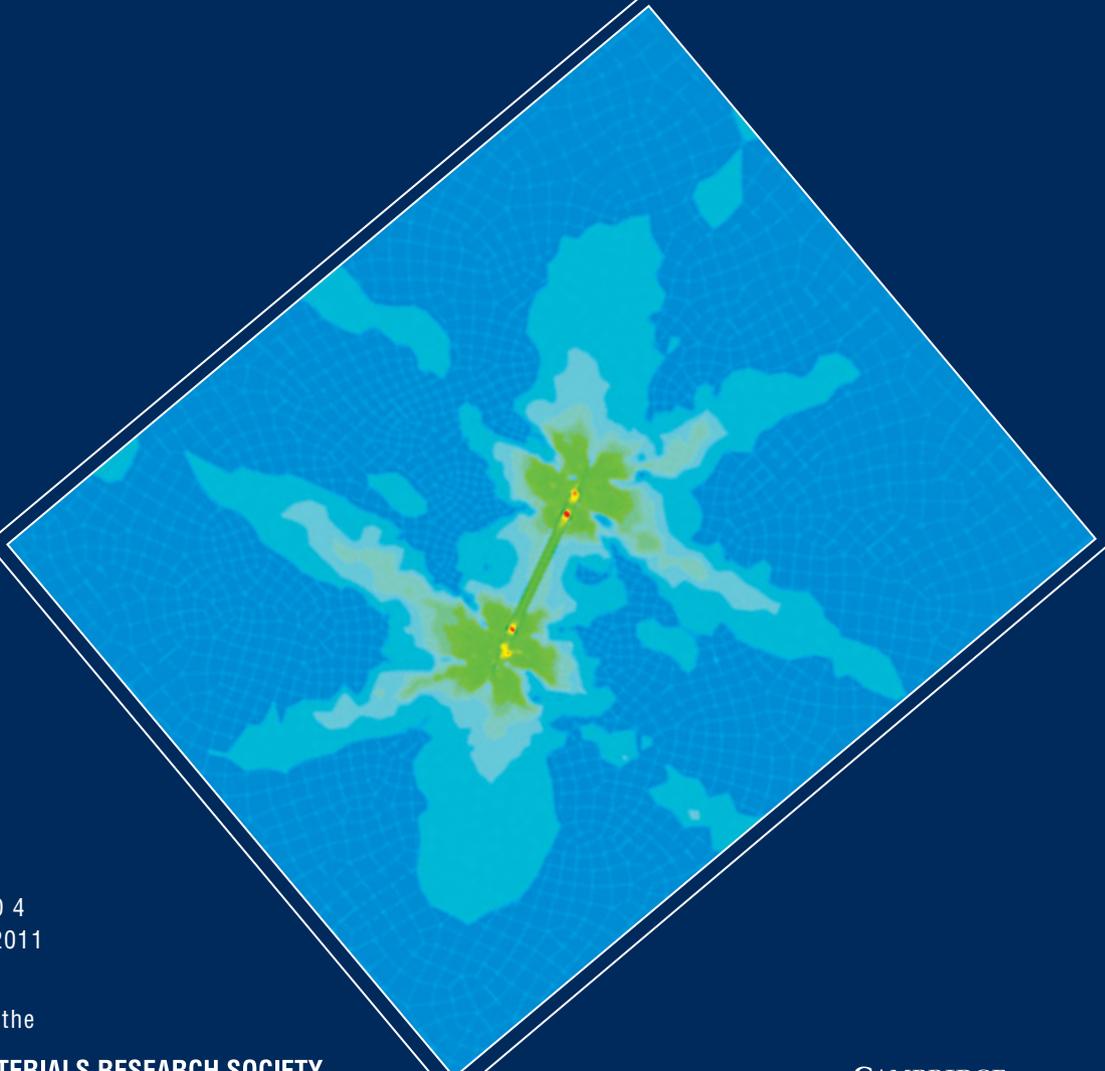




Journal of  
MATERIALS RESEARCH



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Cover: Contours of the normalized shear strength for a precipitate with an initial strain. [K. Elkhodary, W. Lee, L.P. Sun, D.W. Brenner, and M.A. Zikry: Deformation mechanisms of an  $\Omega$  precipitate in a high strength aluminum alloy subjected to high strain rates. p. 487.]

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